(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
5 February 2009 (05.02.2009)

PCT

(10) International Publication Number
WO 2009/017484 A1

(51) International Patent Classification:
B08B 3/00 (2006.01) ***C03C 23/00*** (2006.01)
B08B 3/14 (2006.01) ***C23G 1/00*** (2006.01)
B08B 7/00 (2006.01) ***C23G 5/00*** (2006.01)

(21) International Application Number:
PCT/US2007/017284

(22) International Filing Date: 1 August 2007 (01.08.2007)

(25) Filing Language: English

(26) Publication Language: English

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(81) Designated States *(unless otherwise indicated, for every kind of national protection available)*: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BH, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RS, RU, SC, SD, SE, SG, SK, SL, SM, SV, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

(84) Designated States *(unless otherwise indicated, for every kind of regional protection available)*: ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, LV, MC, MT, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Declaration under Rule 4.17:
— *as to applicant's entitlement to apply for and be granted a patent (Rule 4.17(ii))*

Published:
— *with international search report*

(54) **Title:** STRIPPING AND REMOVAL OF ORGANIC-CONTAINING MATERIALS FROM ELECTRONIC DEVICE SUBSTRATE SURFACES

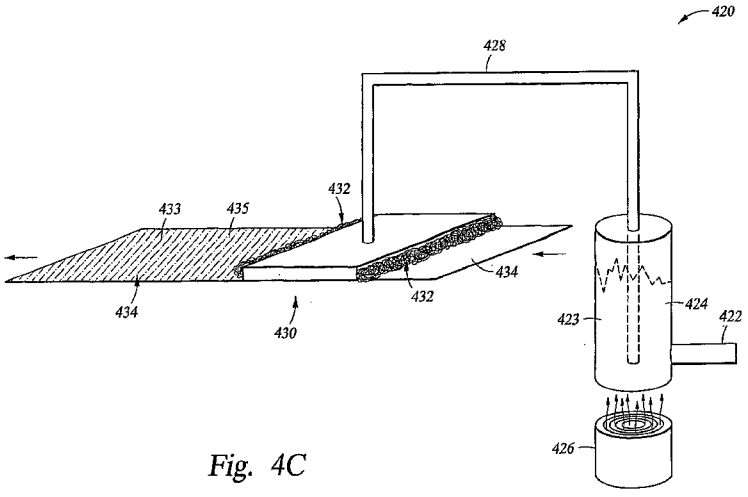


Fig. 4C

(57) **Abstract:** Described herein is a method of removing an organic-containing material from an exposed surface of a large substrate (at least 0.25 m^2). The substrate may comprise an electronic device. The exposed surface is treated with a stripping solution comprising ozone (O_3) in a solvent, where the solvent comprises acetic anhydride. The stripping solvent used to form the stripping solution may comprise a mixture of acetic anhydride with a co-solvent selected from the group consisting of a carbonate containing 2 - 4 carbon atoms, ethylene glycol diacetate, and combinations thereof. In some instances, the stripping solution, may contain only acetic anhydride and ozone, where the ozone concentration is typically about 300 ppm or greater.

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